Supplemental Section 2 – List of Photolithographic Masks

Mask Name	**Side of Wafer**	**Description**
Mask1-Alignment	Top	Wafer front-side alignment marks used to align all subsequent mask layers.
Mask1-Alignment_Closeup	Top	Detail of alignment marks on one side of wafer.
Mask2-Oxide	Top	Thermally-grown silicon dioxide pattern for electrical isolation.
Mask3-Resistor	Top	Pattern for the polysilicon piezoresistors on the front-side of the wafer.
Mask4-Cavity	Back	Pattern on back-side to form both the cavity (to fill with water) and the diaphragm.
Mask5-Metal	Top	Metal wires connecting the piezoresistors with the contact pads.
Mask6-Vias	Top	Pattern to open holes (vias) over the metal pads through the passivation layers.